



US00D353817S

United States Patent [19]
Wada

[11] **Patent Number: Des. 353,817**
[45] **Date of Patent: ** Dec. 27, 1994**

[54] **HEADPHONE**

[75] **Inventor: Joh Wada, Tokyo, Japan**
[73] **Assignee: Sony Corporation, Tokyo, Japan**
[**] **Term: 14 Years**
[21] **Appl. No.: 4,444**
[22] **Filed: Feb. 5, 1993**

[30] **Foreign Application Priority Data**

Aug. 28, 1992 [JP] Japan 4-25511
[52] **U.S. Cl. D14/205**
[58] **Field of Search D14/205; 381/183, 187,**
381/188; 379/430, 444

[56] **References Cited**

U.S. PATENT DOCUMENTS

D. 331,059 11/1992 Sogabe et al. D14/205
5,068,923 12/1991 Sjöqvist 381/188

OTHER PUBLICATIONS

Hong Kong Enterprise; Jun. 1991; p. 130; Headphone
(upper right).

Stereo Review; Aug. 1990; p. 63; Headphone (upper
right).
Stereo Review; Jan. 1990; p. 14; Headphone (upper
left).
Stereo Review; Jun. 1985; p. 14; Headphone (upper
left).

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[57] **CLAIM**

The ornamental design for a headphone, as shown and
described.

DESCRIPTION

FIG. 1 is a top, front and right-side perspective view of
a headphone, showing my new design;
FIG. 2 is a top, front and right-side perspective view
thereof, shown in the folded position;
FIG. 3 is a reduced front elevational view thereof;
FIG. 4 is a reduced rear elevational view thereof;
FIG. 5 is a reduced left side elevational view thereof;
FIG. 6 is a reduced right side elevational view thereof;
FIG. 7 is a reduced top plan view thereof; and,
FIG. 8 is a reduced bottom plan view thereof.

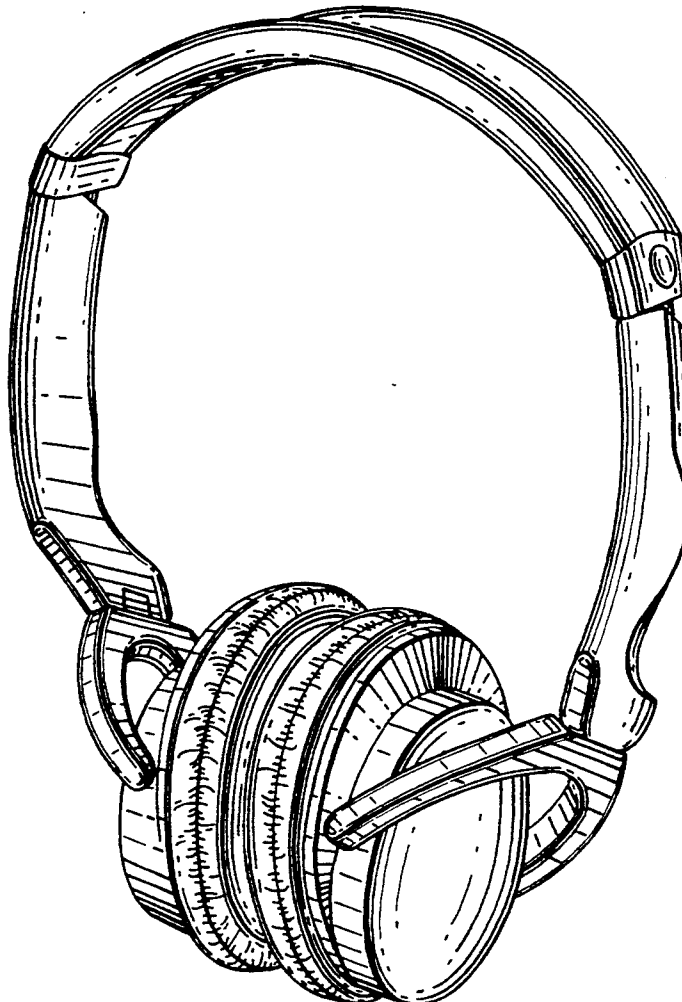


FIG. 1

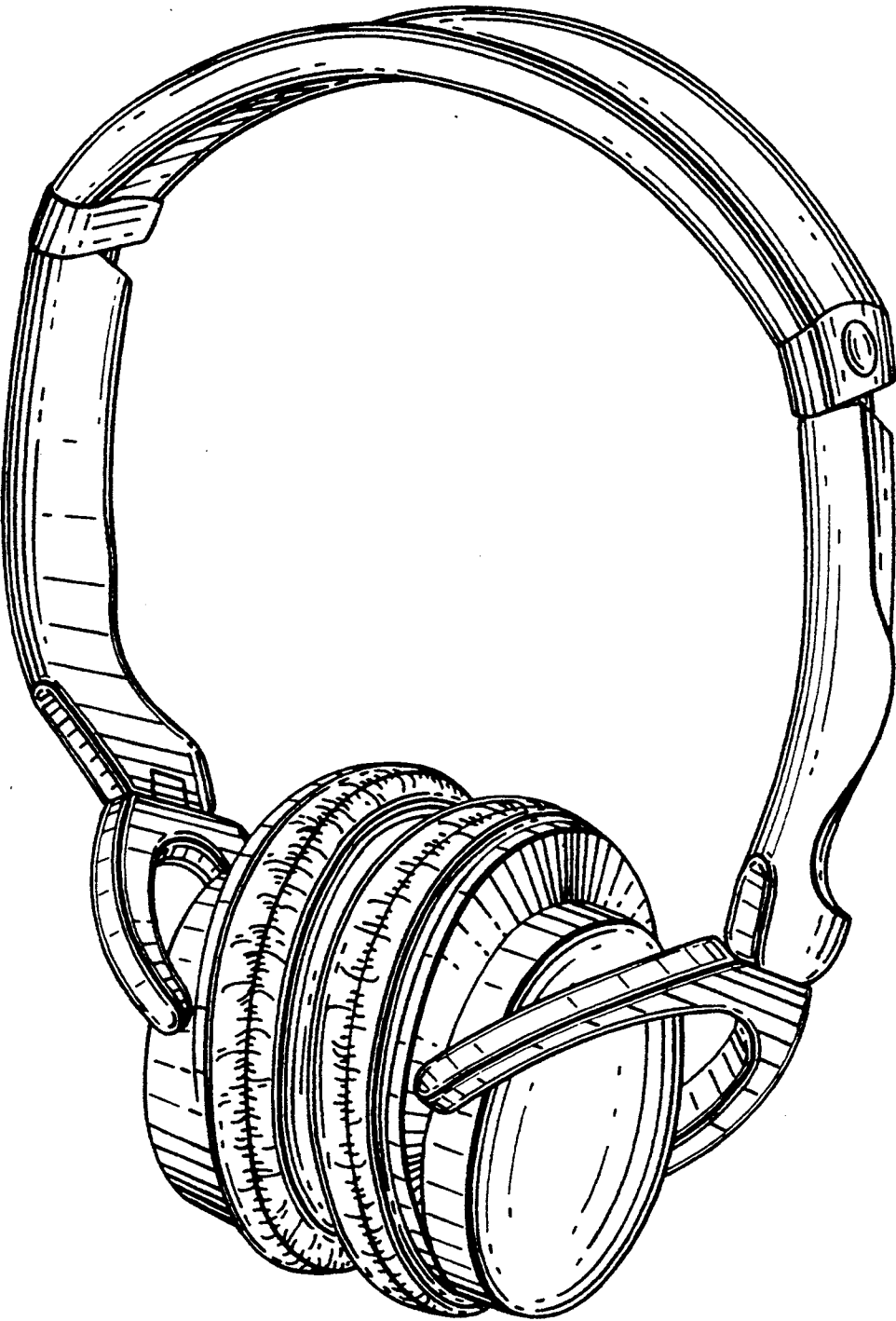


FIG. 2

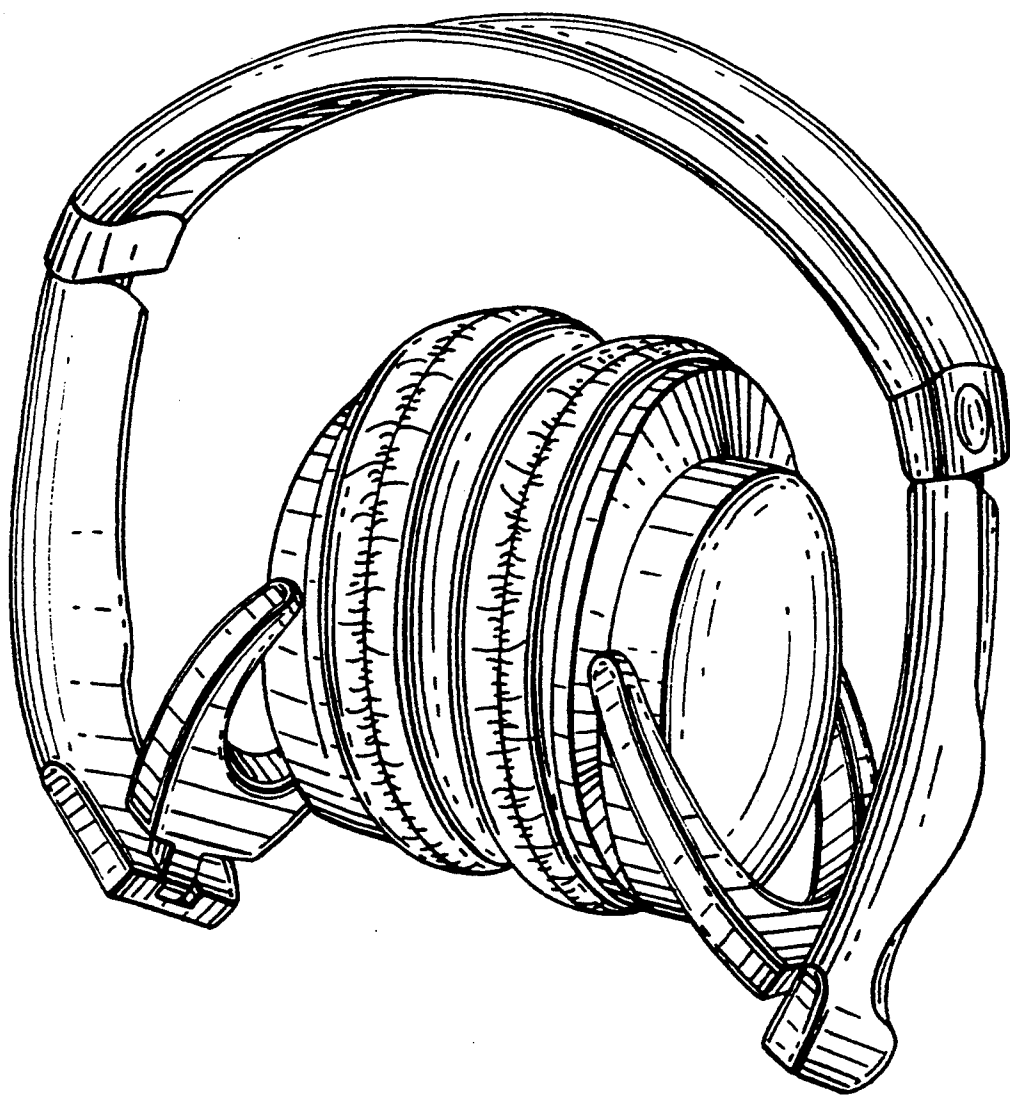


FIG. 3

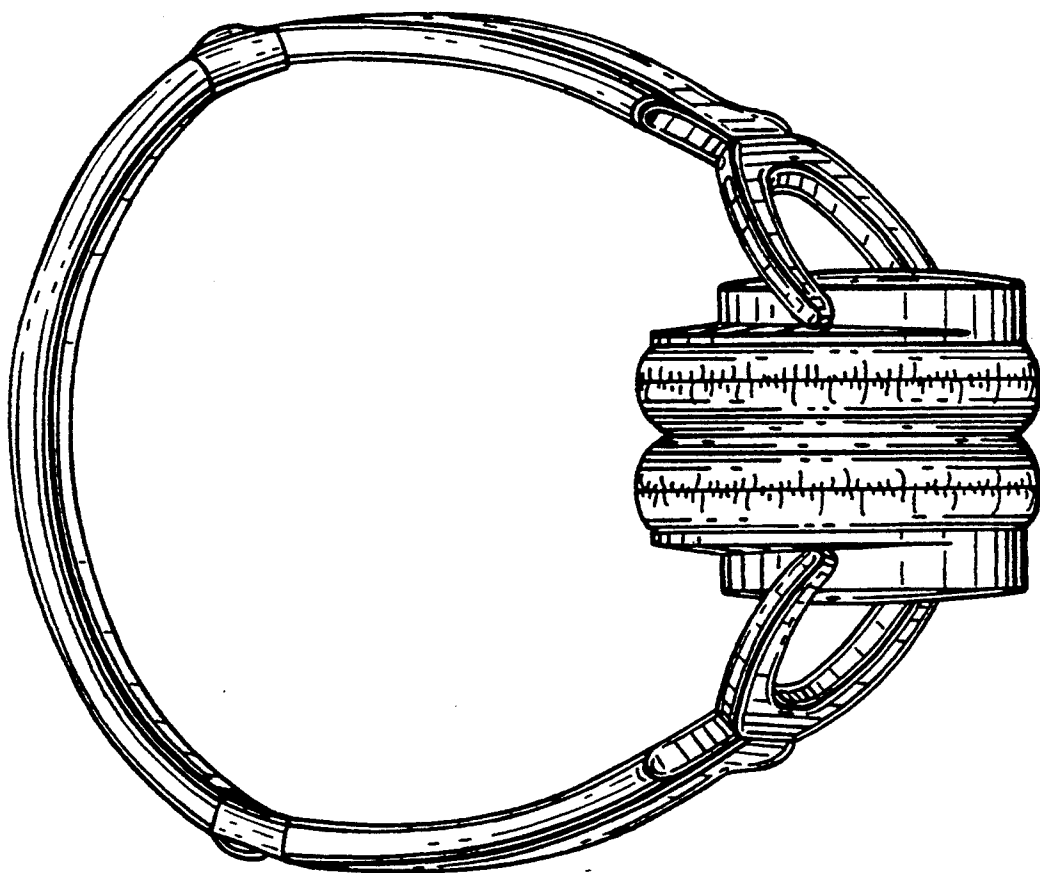


FIG. 5

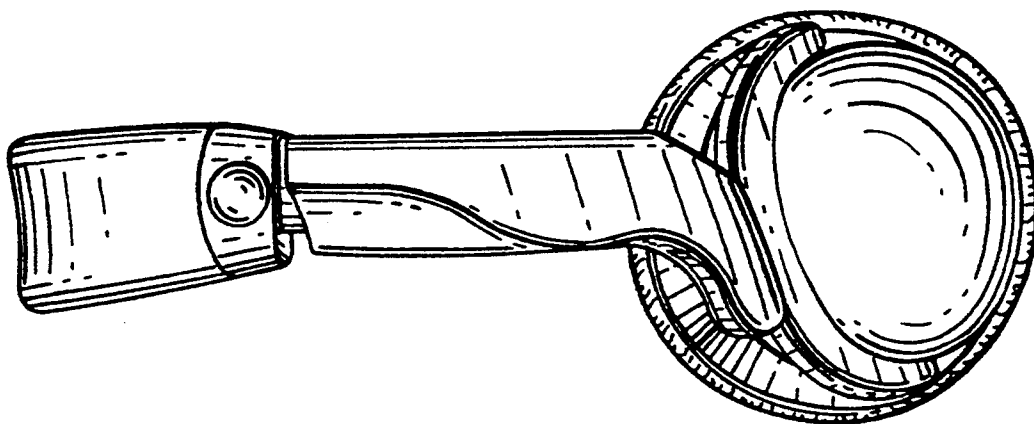


FIG. 4

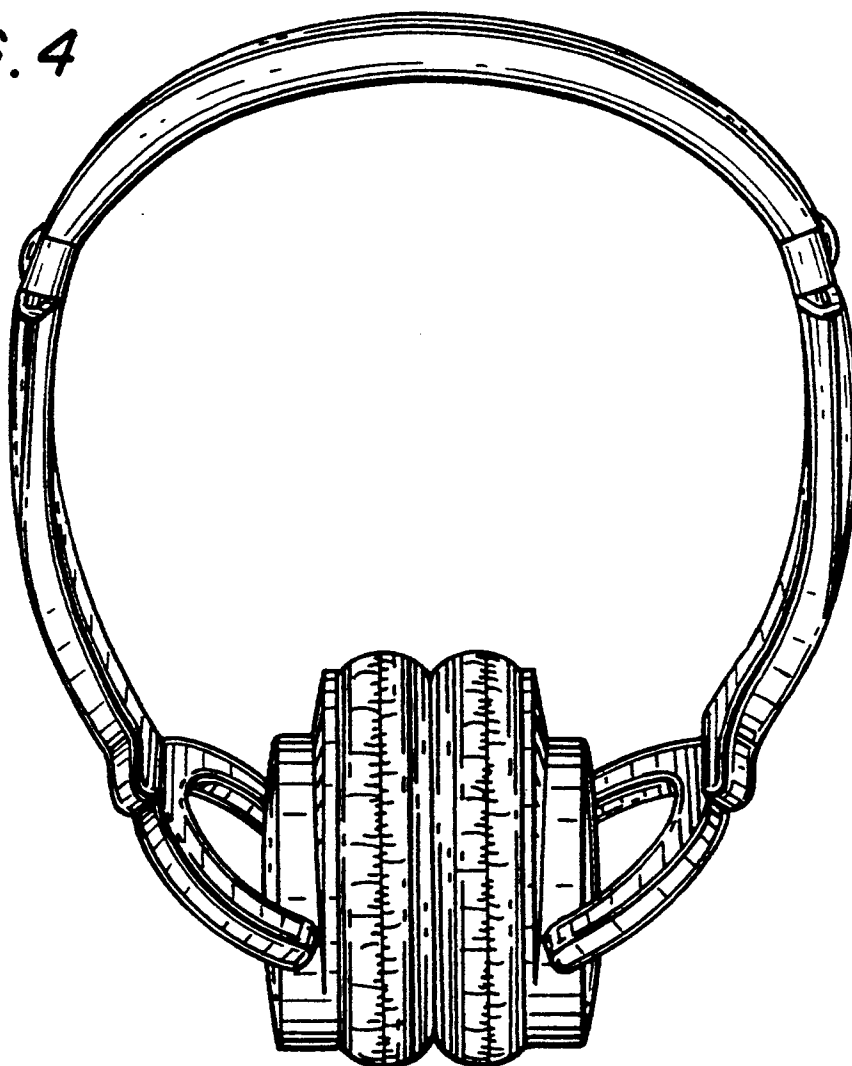


FIG. 8

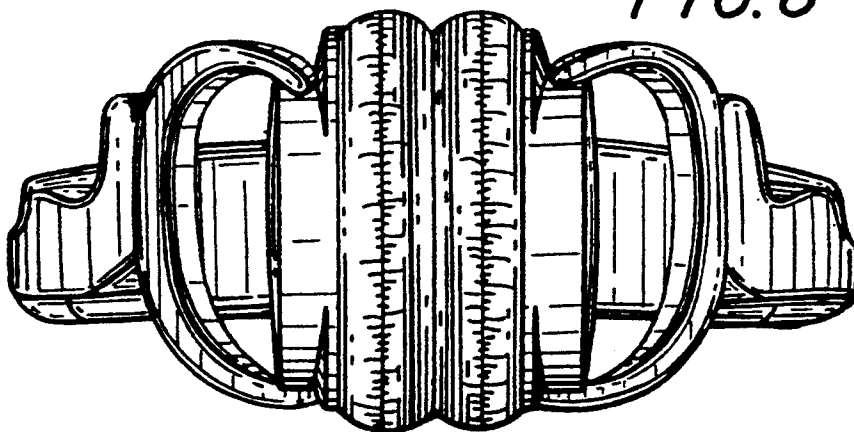


FIG. 6

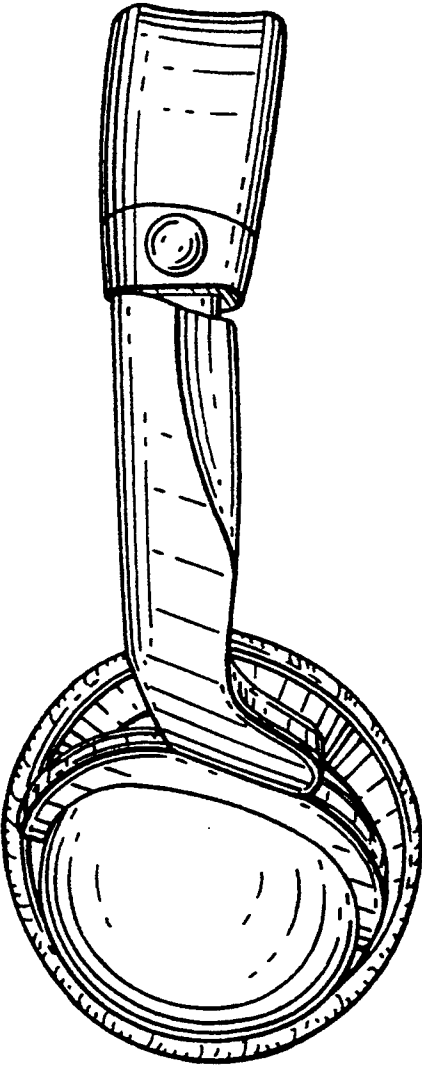


FIG. 7

